Special Issue

Recent Advances in Thin-Film Devices

Message from the Guest Editors

A thin film is defined as a low-dimensional material, which is a condensed one-by-one atomic/ molecular/ ionic species of matter. The thickness is typically less than several microns. Thin-film materials are based on micro/nano structures and its devices have various applications. The classes of materials include silicon, carbon, glasses, polymers (plastics), metals, ceramics, composites, liquid crystals, colloids, semiconductors, and superconductors, as well as magnetic, optical, photonic, optoelectronic, and nanoscale materials. The goal of this Special Issue is to provide a platform for scientists and academicians all over the world to promote, share, and discuss various new issues and developments in the area of thin-film materials and their applications. In this Special Issue, we intend to invite authors to submit original research on thin-film materials and their applications. Potential topics include, but are not limited to, the following: Thin-film materials and devices; Functional properties of thin films on devices; Micro/nano-scaled microstructures of thin films; Thin-film processes.

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